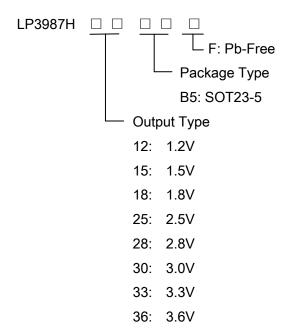


## 600mA, Ultra-low noise, Ultra-Fast CMOS LDO Regulator

### **General Description**

The LP3987H is designed for portable RF and wireless applications with demanding performance and space requirements. The LP3987H performance is optimized for battery-powered systems to deliver ultra low noise and low quiescent current. Regulator ground current increases only slightly in dropout, further prolonging the battery life. The LP3987H also works with low-ESR ceramic capacitors, reducing the amount of board space necessary for power applications, critical in hand-held wireless devices. The LP3987H consumes less than 0.01µA in shutdown mode and has fast turn-on time less than 20µs. The other features include ultra low dropout voltage, high output accuracy, current limiting protection, and high ripple rejection ratio. It is available in the 5-lead of SOT23-5 packages.

#### **Order Information**



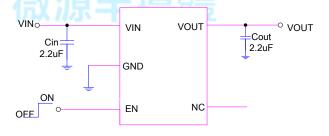
#### **Features**

- Ultra-Low-Noise for RF Application
- 2.5V- 6.0V Input Voltage Range
- ◆ Low Dropout: 360mV @ 600mA
- ♦ High PSSR:-65dB at 1KHz
- < 0.01uA Standby Current When Shutdown</p>
- Ultra-Fast Response in Line/Load transient
- Current Limiting and Thermal Shutdown Protection

### **Applications**

- ♦ Portable Media Players/MP3 players
- ♦ Cellular and Smart mobile phone
- Sensor Module, RF Module

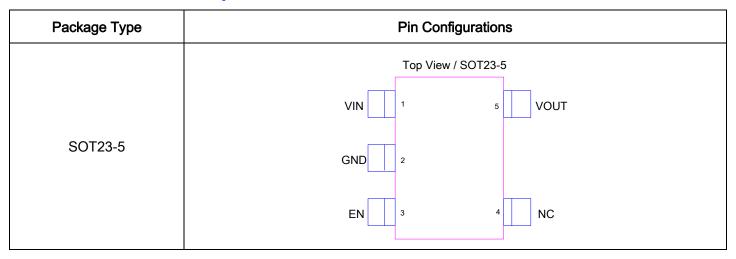
## **Typical Application Circuit**



## **Marking Information**

Device	Marking	Package	Shipping
LP3987H		SOT23-5	3K/REEL

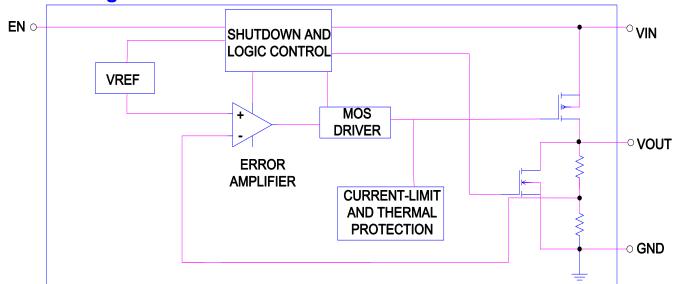
# **Functional Pin Description**



## **Pin Description**

Pin	Name	Description
1	VIN	Power Input Voltage.
2	GND	Ground.
3	EN	Chip Enable (Active High). Note that this pin is high impedance. There is an integrated pull low $1M\Omega$ resistor connected to GND when the control signal is floating.
4	NC	No connection.
5	VOUT	Output Voltage.

# **Function Diagram**



LP3987H-05 May.-2017

# **Absolute Maximum Ratings**

$\diamond$	Input Voltage to GND	0.3V to 6.5V
<b></b>	Other pin to GND	0.3V to 6V
Po	ower Dissipation, PD @ TA = 25°C	
<b></b>	Maximum Power Dissipation ( PD,TA=25°C)	0.5W
Pa	ackage Thermal Resistance	
<b></b>	Thermal Resistance (JA)	195°C/W
<b></b>	Thermal Resistance (JC	60°C/W
<b></b>	Maximum Junction Temperature	150°C
<b></b>	Maximum Soldering Temperature (at leads, 10 sec)	260°C
<b></b>	Storage Temperature Range	65°C to 165°C
ES	SD Susceptibility	
<b></b>	HBM (Human Body Mode)	2kV
<b></b>	MM(Machine-Mode)	200V
Re	ecommended Operating Conditions	
<b></b>	Supply Input Voltage	2.5V to 6V
$\diamond$	Operation Junction Temperature Range	40°C to 125°C
<b></b>	Operation Ambient Temperature Range	40°C to 85°C

LowPowerSemi 微源半導體

LP3987H-05

May.-2017

Email: m Downloaded From Oneyac.com

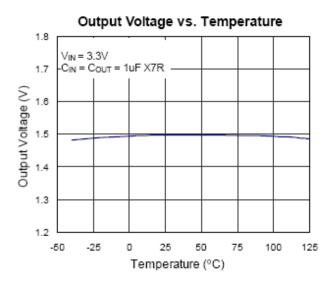


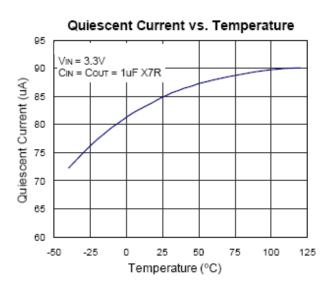
### **Electrical Characteristics**

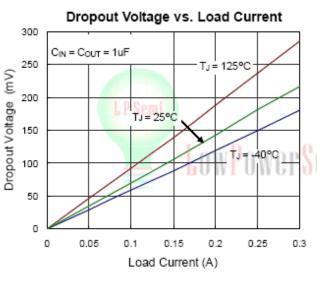
(VIN = VOUT + 0.8V, Cin = Cout =  $1\mu$ F, TA =  $25^{\circ}$  C, unless otherwise specified)

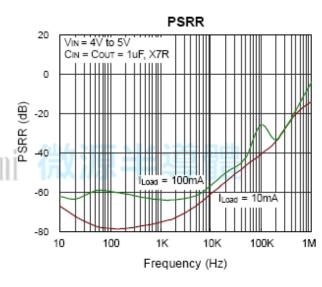
Parameter		Symbol	Test Conditions	Min	Тур.	Max	Units	
Output Voltage Accuracy		$\Delta V_{OUT}$	I <sub>OUT</sub> = 1mA	-2		+2	%	
Output	Output Current		VEN=VIN, VIN>2.5V		600		mA	
Curre	Current Limit		$R_{LOAD} = 1\Omega$		800		mA	
Quiesce	nt Current	IQ	VEN≥1.4V,Output floating		110	130	μΑ	
Dropout Voltage		V <sub>DROP</sub>	I <sub>OUT</sub> =100mA,VOUT> 2.8V		60	80	m)/	
			I <sub>OUT</sub> =600mA,VOUT> 2.8V	360 480		480	mV	
Line Regulation		۸۱/	VIN=(VOUT+1V) to 5.5V,	0.0		0.2	%	
Line Re	eguiation	$\Delta V_{LINE}$	I <sub>OUT</sub> = 1mA			0.2	70	
Load Ro	Load Regulation		1mA < I <sub>OUT</sub> < 300mA			2	%	
Standby	Standby Current		VEN = GND, Shutdown		0.01	1	μΑ	
EN Input E	EN Input Bias Current		VEN = 5V		4	6	μΑ	
	Logic-Low	\/	VIN = 3V to 5.5V,			0.4		
EN Threshold	Voltage	V <sub>IL</sub>	Shutdown				V	
EN THIESHOID	Logic-High	V	VIN = 3V to 5.5V,	4.4	1.4		VIN+	V
	Voltage	V <sub>IH</sub>	Start-Up	1.4		0.3		
Output Noise Voltage		owPowe	10Hz to 100kHz,	4道	100		uVRMS	
			Ι <sub>ουτ</sub> =200mA, Cout=1μF	77	100		UVINIO	
Power Supply	er Supply f = 1kHz PSRR Cout = 1µF,			-65		dB		
Rejection Rate f = 10kHz			I <sub>OUT</sub> = 10mA		-55			
Thermal Shutdown Temperature		T <sub>SD</sub>			150		°C	

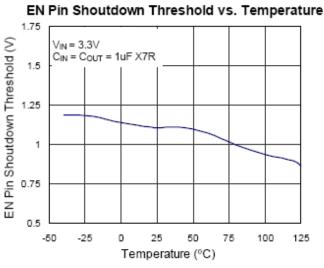
## **Typical Operating Characteristics**

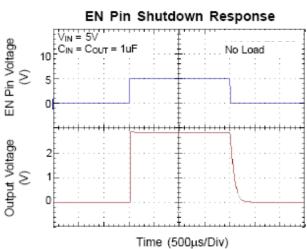












LP3987H-05 May.-2017

### **Applications Information**

Like any low-dropout regulator, the external capacitors used with the LP3987H must be carefully selected for regulator stability and performance. Using a capacitor whose value is > 1µF on the LP3987H input and the amount of capacitance can be increased without limit. The input capacitor must be located a distance of not more than 0.5 inch from the input pin of the IC and returned to a clean analog ground. There is a special attention which is the input capacitance should not be less than output capacitance. Any good quality ceramic or tantalum can be used for this capacitor. The capacitor with larger value and lower ESR (equivalent series resistance) provides better PSRR and line-transient response. The output capacitor must meet both requirements for minimum amount of capacitance and ESR in all LDOs application. The LP3987H is designed specifically to work with low ESR ceramic output capacitor in space-saving and performance consideration. Using a ceramic capacitor whose value is at least  $1\mu F$  with ESR is >  $25m\Omega$  on the LP3987H output ensures stability. The LP3987H still works well with output capacitor of other types due to the wide stable ESR range. Output capacitor of larger capacitance can reduce noise and improve load transient response, stability, and PSRR. The output capacitor should be located not more than 0.5 inch from the VOUT pin of the LP3987H and returned to a clean analog ground.

#### **Thermal Considerations**

Thermal protection limits power dissipation in LP3987H. When the operation junction temperature exceeds 150°C, the OTP circuit starts the thermal shutdown function turn the pass element off. The pass element turns on again after the junction temperature cools by 25°C. For continue operation, do not exceed absolute maximum operation junction temperature 125°C.

The power dissipation definition in device is:

$$P_D = (VIN-VOUT) \times I_{OUT} + VIN \times I_Q$$

The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surroundings airflow and temperature difference between junction to ambient.

The maximum power dissipation can be calculated by following formula:

$$P_{D(MAX)} = (T_{J(MAX)} - T_A)/\theta_{JA}$$

Where TJ(MAX) is the maximum operation junction temperature 125°C, TA is the ambient temperature and the θJA is the junction to ambient thermal resistance. For recommended operating conditions specification of LP3987H, where TJ(MAX) is the maximum junction temperature of the die

(125°C) and TA is the maximum ambient temperature. The junction to ambient thermal resistance (θJA is layout dependent) for SOT23-5 package is 195°C/W.

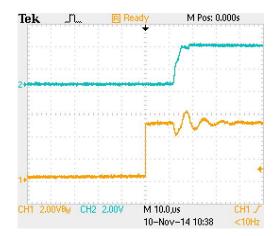
$$P_{D(MAX)} = (125^{\circ}C - 25^{\circ}C) / 195^{\circ}C = 500 \text{mW (SOT23-5)}$$

The maximum power dissipation depends on operating ambient temperature for fixed TJ(MAX) and thermal resistance θJA. When considering the thermal characteristic of PCB it may be larger than 500mW.

Email: m Downloaded From Oneyac.com

#### **Start-up Function Enable Function**

The LP3987H features LDO regulator enable/disable function. To assure the LDO regulator will switch on, the EN turn on control level must be greater than 1.4 volts. The LDO regulator will go into the shutdown mode when the voltage on the EN pin falls below 0.4 volts. For to protecting the system, the LP3987H have a quick-discharge function. If the enable function is not needed in a specific application, it may be tied to VIN to keep the LDO regulator in a continuously on state.

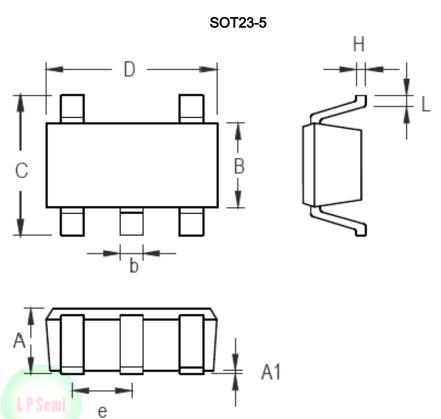




LP3987H-05 May.-2017



# **Packaging Information**



LowPowerSemi 微源半導

	U 11 U 11		17 707 1773 7	Y	
Cumbal	Dimensions Ir	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.889	1.295	0.035	0.051	
A1	0.000	0.152	0.000	0.006	
В	1.397	1.803	0.055	0.071	
b	0.356	0.559	0.014	0.022	
С	2.591	2.997	0.102	0.118	
D	2.692	3.099	0.106	0.122	
е	0.838	1.041	0.033	0.041	
Н	0.080	0.254	0.003	0.010	
L	0.300	0.610	0.012	0.024	

SOT-23-5 Surface Mount Package

# 单击下面可查看定价,库存,交付和生命周期等信息

>>LOW POWER(微源半导体)